

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
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EPAS ID: PAT2882052

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JIN HO KANG	05/08/2014
CHEOL PARK	05/08/2014
GODFREY SAUTI	04/16/2014
LUKE GIBBONS	04/30/2014
RECEIVING PARTY DATA	
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City:	HAMPTON
State/Country:	VIRGINIA
Postal Code:	23666-6157
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14279601
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Address Line 4:	NORFOLK, VIRGINIA 23514-3037
ATTORNEY DOCKET NUMBER:	LAR 18005-1/0156139
NAME OF SUBMITTER:	ROBERT E. SMARTSCHAN
SIGNATURE:	/Robert E. Smartschan/
DATE SIGNED:	06/03/2014
Total Attachments: 4	
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THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Docket No.: LAR 18005-1/0156139

Jin Ho KANG (et al.)

Filed: May 16, 2014

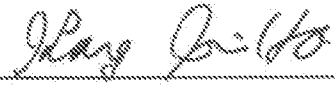
Application No.

For: **RADIATION HARDENED MICROELECTRONIC CHIP PACKAGING
TECHNOLOGY**

ASSIGNMENT AND INVENTORSHIP DECLARATION

I, Jin Ho Kang, residing at 802 E. Willow Point Place, do hereby claim and declare that I am a true, first inventor of an invention relating to and entitled RADIATION HARDENED MICROELECTRONIC CHIP PACKAGING TECHNOLOGY, for which an application for a United States Patent is being filed on even date herewith or shortly thereafter in the U.S. Patent and Trademark Office, Attorney's/Agent's Docket No. LAR 18005-1/0156139, and do hereby assign, transfer and declare unto NATIONAL INSTITUTE OF AEROSPACE ASSOCIATES, 100 Exploration Way, Hampton, Virginia 23666-6157, all of my right, title and interest throughout the world in and to the application and to the invention, and in all divisional, continuing, or substitute applications in any and all countries, and in and to any Letters Patent that may be issued for said invention in any and all countries; and consent to the recordal of this assignment being under covenant, not only that I have full power to make same, but also that such assigned rights are not encumbered by any grant, license, or other right heretofore given.

Subscribed and sworn by me at Newport News, VA this 8th day of May, 2014.



Jin Ho Kang

13109453v1

THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Docket No.: LAR 18005-1/0156139

Jin Ho KANG (et al.)

Filed: May 16, 2014

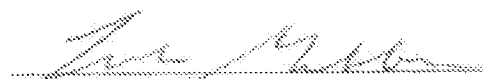
Application No.

For: RADIATION HARDENED MICROELECTRONIC CHIP PACKAGING
TECHNOLOGY

ASSIGNMENT AND INVENTORSHIP DECLARATION

I, Luke Gibbons, residing at 5305 Sloane Square, Williamsburg, VA 23188, do hereby claim and declare that I am a true, first inventor of an invention relating to and entitled RADIATION HARDENED MICROELECTRONIC CHIP PACKAGING TECHNOLOGY, for which an application for a United States Patent is being filed on even date herewith or shortly thereafter in the U.S. Patent and Trademark Office, Attorney's/Agent's Docket No. LAR 18005-1/0156139, and do hereby assign, transfer and declare unto NATIONAL INSTITUTE OF AEROSPACE ASSOCIATES, 100 Exploration Way, Hampton, Virginia 23666-6157, all of my right, title and interest throughout the world in and to the application and to the invention, and in all divisional, continuing, or substitute applications in any and all countries, and in and to any Letters Patent that may be issued for said invention in any and all countries; and consent to the recordal of this assignment being under covenant, not only that I have full power to make same, but also that such assigned rights are not encumbered by any grant, license, or other right heretofore given.

Subscribed and sworn by me at HAMPTON, VA this 30 day of APRIL, 2014.


Luke Gibbons

(3195628)

THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Docket No.: LAR 18005-1/0156139

Jin Ho KANG (et al.)

Filed: May 16, 2014

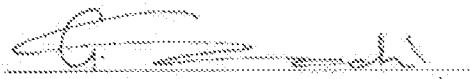
Application No.

For: **RADIATION HARDENED MICROELECTRONIC CHIP PACKAGING
TECHNOLOGY**

ASSIGNMENT AND INVENTORSHIP DECLARATION

I, Godfrey Sauti, residing at 1501 Wyndham Drive, Hampton, VA 23666, do hereby claim and declare that I am a true, first inventor of an invention relating to and entitled RADIATION HARDENED MICROELECTRONIC CHIP PACKAGING TECHNOLOGY, for which an application for a United States Patent is being filed on even date herewith or shortly thereafter in the U.S. Patent and Trademark Office, Attorney's/Agent's Docket No. LAR 18005-1/0156139, and do hereby assign, transfer and declare unto NATIONAL INSTITUTE OF AEROSPACE ASSOCIATES, 100 Exploration Way, Hampton, Virginia 23666-6157, all of my right, title and interest throughout the world in and to the application and to the invention, and in all divisional, continuing, or substitute applications in any and all countries, and in and to any Letters Patent that may be issued for said invention in any and all countries; and consent to the recordal of this assignment being under covenant, not only that I have full power to make same, but also that such assigned rights are not encumbered by any grant, license, or other right heretofore given.

Subscribed and sworn by me at Hampton, VA this 16th day of April, 2014.


Godfrey Sauti

13109254v1

THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Docket No.: LAR 18005-1/0156139

Jin Ho KANG (et al.)

Filed: May 16, 2014

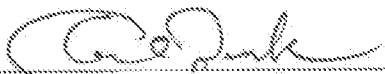
Application No.

For: **RADIATION HARDENED MICROELECTRONIC CHIP PACKAGING
TECHNOLOGY**

ASSIGNMENT AND INVENTORSHIP DECLARATION

I, Cheol Park, residing at 207 Clayton Drive, Yorktown, VA 23693, do hereby claim and declare that I am a true, first inventor of an invention relating to and entitled RADIATION HARDENED MICROELECTRONIC CHIP PACKAGING TECHNOLOGY, for which an application for a United States Patent is being filed on even date herewith or shortly thereafter in the U.S. Patent and Trademark Office, Attorney's/Agent's Docket No. LAR 18005-1/0156139, and do hereby assign, transfer and declare unto NATIONAL INSTITUTE OF AEROSPACE ASSOCIATES, 100 Exploration Way, Hampton, Virginia 23666-6157, all of my right, title and interest throughout the world in and to the application and to the invention, and in all divisional, continuing, or substitute applications in any and all countries, and in and to any Letters Patent that may be issued for said invention in any and all countries; and consent to the recordal of this assignment being under covenant, not only that I have full power to make same, but also that such assigned rights are not encumbered by any grant, license, or other right heretofore given.

Subscribed and sworn by me at Hampton, VA this 8th day of May, 2014.


Cheol Park

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